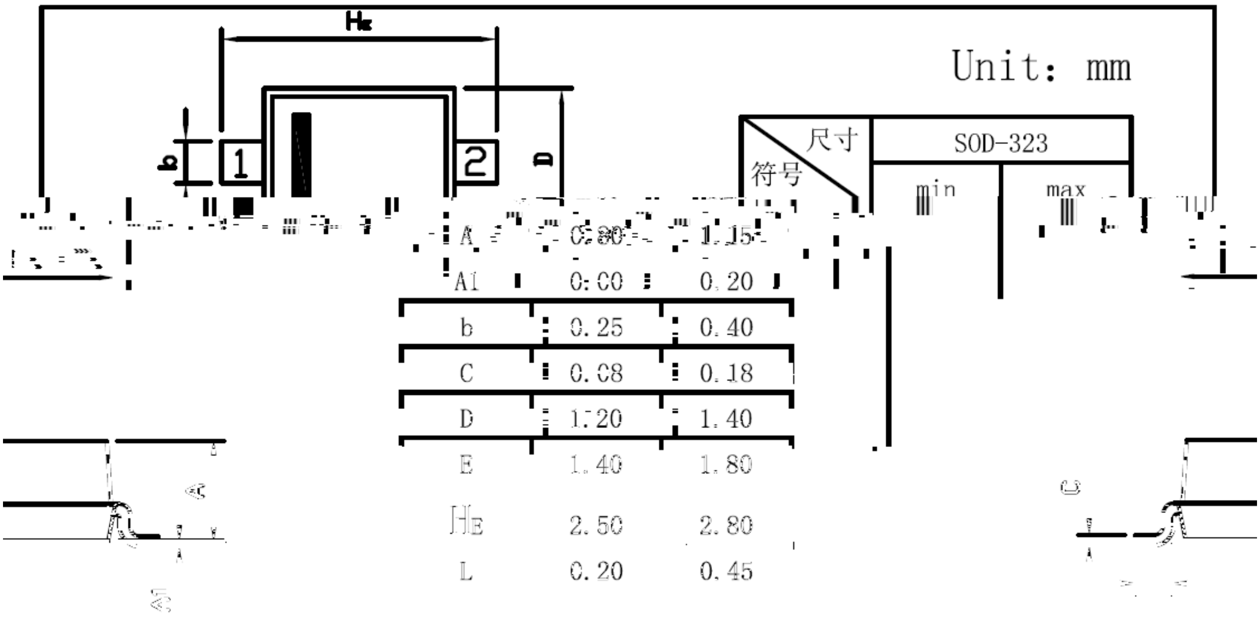
[redacted]

[redacted]	Symbol	Rating	Unit
[redacted]	V_{RRM}	10	V
[redacted]	I_F	3	A
[redacted]	I_{FSM}	20	A
[redacted]	P_D	350	mW
[redacted]	T_J,T_{stg}	-55 ~ +150	

[redacted]	Test Conditions	Rating	Unit
[redacted]	I_F=10mA	0.30	V
[redacted]	I_F=100mA	0.38	
[redacted]	I_F=500mA	0.50	
[redacted]	I_F=1000mA	0.60	

/ Package Dimensions



符号 \ 尺寸	SOD-323 min	SOD-323 max
A	0.80	1.15
A1	0.00	0.20
b	0.25	0.40
C	0.08	0.18
D	1.20	1.40
E	1.40	1.80
HE	2.50	2.80
L	0.20	0.45

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:	
1 150 180 60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2 245±5 5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3 2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units	Dimension	(unit mm^3)